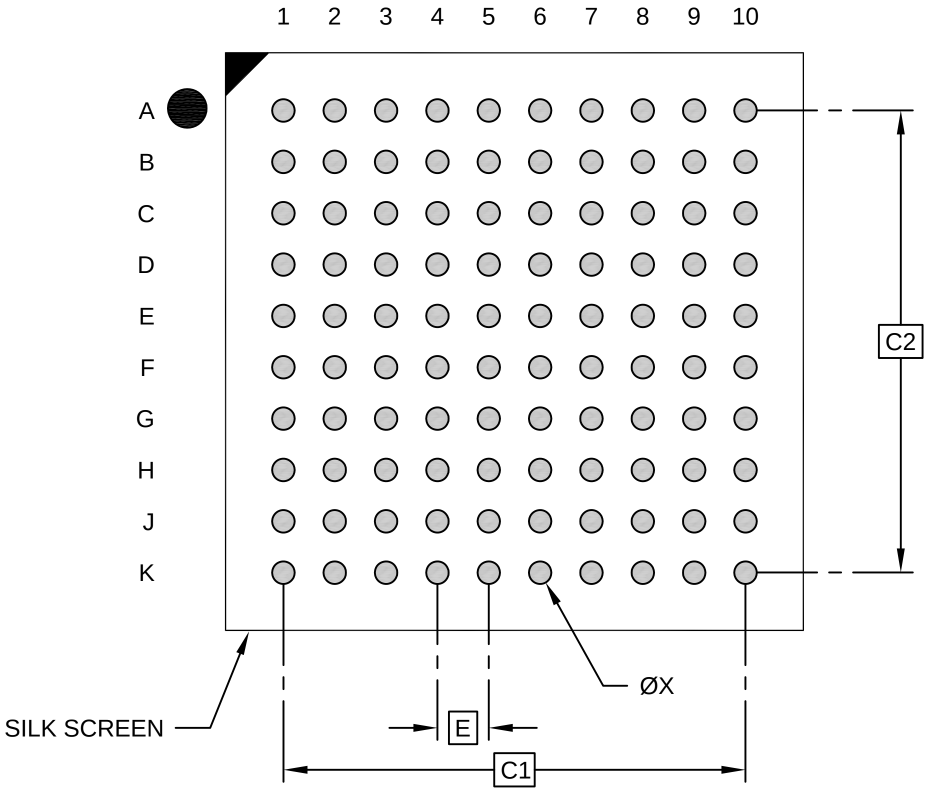
100-Ball Ceramic Ball Grid Array Package (A2B) - 9x9 mm Body [TFGA]
Atmel Legacy Global Package Code CPR

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.58 BSC	
Overall Pitch	C1		7.20 BSC	
Contact Pad Spacing	C2		7.20 BSC	
Contact Pad Diameter (X100)	X1			0.35

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process